

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 11-126037

(43)Date of publication of application : 11.05.1999

(51)Int.Cl.

G09F 9/33
H01L 33/00

(21)Application number : 09-291029

(71)Applicant : FUTABA CORP

(22)Date of filing : 23.10.1997

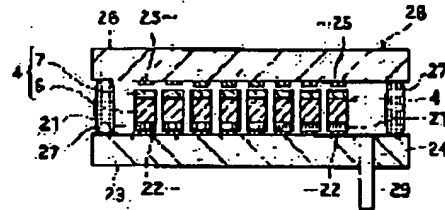
(72)Inventor : HONDA KENICHI
MAKITA YOSHIO
NAMIKAWA MAMORU

(54) SEMICONDUCTOR DISPLAY DEVICE AND ITS PRODUCTION

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor display device producing method simple in production process and high in the positioning precision of light emitting diode elements.

SOLUTION: An adhesive tape is stuck to an electrically conductive substrate and the substrate side of a wafer having a light emitting diode layer. Then, the wafer is divided to form plural light emitting elements 4. An operating means is used to suck in the elements 4 from plural positioning holes and to hold the elements 4. Then, the strength of the adhesive tape is reduced, and the tape is arranged at the location close to the elements 4, and the elements 4 are sucked in to hold the elements 4 in the holes. Then, an adhesive 21 is applied on the base body 6 side of the elements 4 being held. Then, the base body 6 side of the elements 4 are adhered to the prescribed positions of the inner surface of a back surface substrate 23. Then, a light emitting diode 7 of the element 4 and the inner surface of a transparent front surface substrate 26 are placed opposing to each other and an elastic sealing material 27 is provided between the both substrates. Then, the inner section of the inner space is evacuated, sealed and the inner surface of the substrate 26 is contacted to the diodes 7 and fixed.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]